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April 30, 2025

Internship Recruitment Team

Dear Internship Recruitment Team,

I am an enthusiastic BSc Electrical and Telecommunication Engineering student at Multimedia University of Kenya, expected to graduate in December 2027. I am writing to express my keen interest in any available attachment opportunities that can help me apply my skills and gain industry experience in the field of networking, datacom, and telecommunications. I will be available as from early June for three months as per my academic calendar.

Throughout my academic journey, I have actively gained hands-on experience to complement my coursework. I have carried out a wide range of practical labs using Huawei eNSP, including IPv4/IPv6 routing, OSPF, VLANs, Spanning Tree, ACLs, NAT, DHCP, WLANs, and more. You can view these labs in detail here: [github.com/plochoidysis-ojwege/eNSP-labs](https://github.com/plochoidysis-ojwege/eNSP-labs).

I possess technical proficiency in TCP/IP, OSPF, VLANs, MATLAB, AutoCAD, and Python and C programming. My participation in the IEEE Student Branch has helped me embrace teamwork, leadership, and communication skills.

I am excited about the opportunity to contribute to a forward thinking organization and continue building on the skills and knowledge I've developed. Thank you for considering my application. I would appreciate the chance to further discuss how I can contribute value as an intern.

Sincerely,

Onyango Denzel Ninga

encl: Curriculum Vitae